BSS123LT1G, BVSS123LT1G

Power MOSFET 170 mAmps, 100 Volts

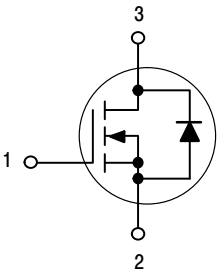
N−Channel SOT−23

ON Semiconductor®

http://onsemi.com

170 mAMPS
100 VOLTS
$R_{DS(on)}$ = 6 Ω

N−Channel



Features

- AEC−Q101 Qualified and PPAP Capable − BVSS123LT1G
- These Devices are Pb−Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain−Source Voltage	V_{DSS}	100	Vdc
Gate−Source Voltage − Continuous − Non−repetitive ($t_p \le 50$ μs)	 V_{GS} V_{GSM}	 ±20 ±40	 Vdc Vpk
Drain Current − Continuous (Note 1) − Pulsed (Note 2)	 I_D I_{DM}	 0.17 0.68	Adc

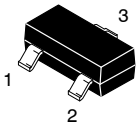
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

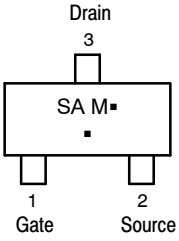
Characteristic	Symbol	Max	Unit
Total Device Dissipation FR−5 Board (Note 3) T_A = 25°C Derate above 25°C	P_D	 225 1.8	 mW mW/°C
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	556	°C/W
Junction and Storage Temperature	T_J, T_{stg}	−55 to +150	°C

1. The Power Dissipation of the package may result in a lower continuous drain current.
2. Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.
3. FR−5 = 1.0 × 0.75 × 0.062 in.

MARKING DIAGRAM & PIN ASSIGNMENT



SOT−23
CASE 318
STYLE 21



SA = Device Code
M = Date Code
▪ = Pb−Free Package

(*Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Drain−Source Breakdown Voltage (V_{GS} = 0, I_D = 250 μAdc)	$V_{(BR)DSS}$	100	–	–	Vdc
Zero Gate Voltage Drain Current (V_{GS} = 0, V_{DS} = 100 Vdc) T_J = 25°C T_J = 125°C	I_{DSS}	– –	– –	15 60	μAdc
Gate−Body Leakage Current (V_{GS} = 20 Vdc, V_{DS} = 0)	I_{GSS}	–	–	50	nAdc
ON CHARACTERISTICS (Note 4)					
Gate Threshold Voltage (V_{DS} = V_{GS}, I_D = 1.0 mAdc)	$V_{GS(th)}$	0.8	–	2.8	Vdc
Static Drain−Source On−Resistance (V_{GS} = 10 Vdc, I_D = 100 mAdc)	$r_{DS(on)}$	–	5.0	6.0	Ω
Forward Transconductance (V_{DS} = 25 Vdc, I_D = 100 mAdc)	g_{fs}	80	–	–	mmhos
DYNAMIC CHARACTERISTICS					
Input Capacitance (V_{DS} = 25 Vdc, V_{GS} = 0, f = 1.0 MHz)	C_{iss}	–	20	–	pF
Output Capacitance (V_{DS} = 25 Vdc, V_{GS} = 0, f = 1.0 MHz)	C_{oss}	–	9.0	–	pF
Reverse Transfer Capacitance (V_{DS} = 25 Vdc, V_{GS} = 0, f = 1.0 MHz)	C_{rss}	–	4.0	–	pF
SWITCHING CHARACTERISTICS[4]					
Turn−On Delay Time (V_{CC} = 30 Vdc, I_C = 0.28 Adc, V_{GS} = 10 Vdc, R_{GS} = 50 Ω)	$t_{d(on)}$	–	20	–	ns
Turn−Off Delay Time	$t_{d(off)}$	–	40	–	ns
REVERSE DIODE					
Diode Forward On−Voltage (I_D = 0.34 Adc, V_{GS} = 0 Vdc)	V_{SD}	–	–	1.3	V

4. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

ORDERING INFORMATION

Device	Package	Shipping†
BSS123LT1G	SOT−23 (Pb−Free)	3000 / Tape & Reel
BSS123LT3G	SOT−23 (Pb−Free)	10000 / Tape & Reel
BVSS123LT1G	SOT−23 (Pb−Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

TYPICAL ELECTRICAL CHARACTERISTICS

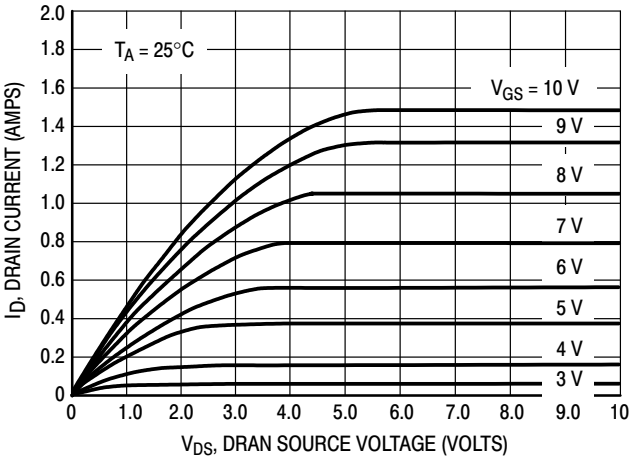


Figure 1. Ohmic Region

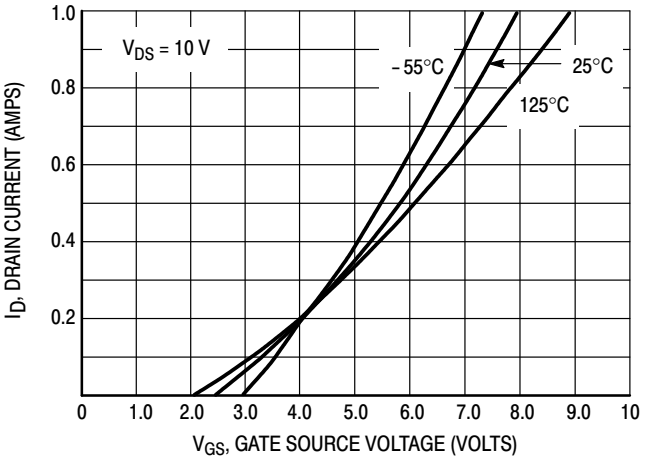


Figure 2. Transfer Characteristics

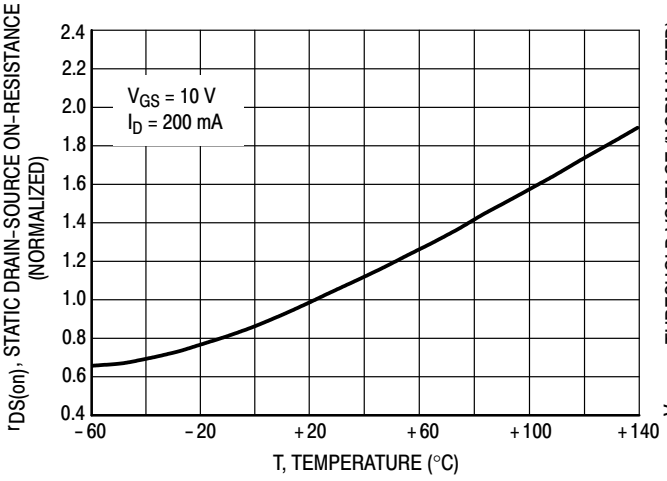


Figure 3. Temperature versus Static Drain−Source On−Resistance

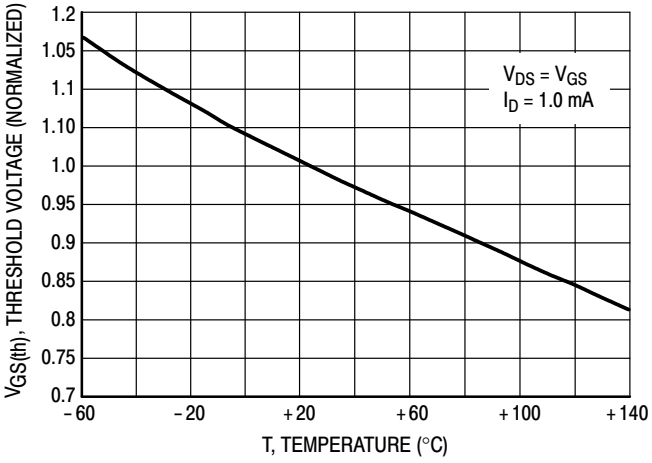


Figure 4. Temperature versus Gate Threshold Voltage

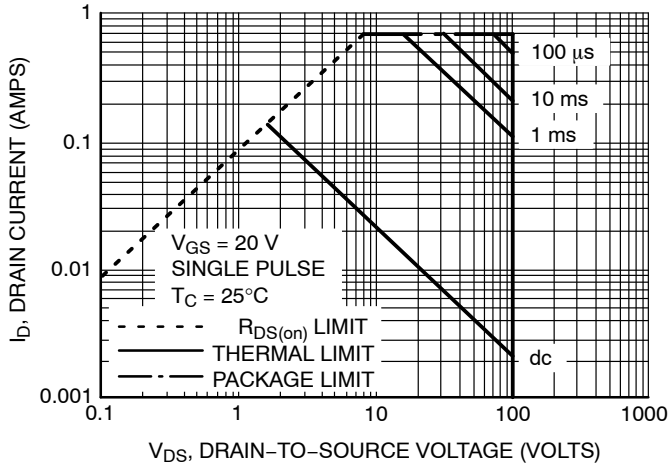


Figure 5. Maximum Rated Forward Biased Safe Operating Area

TYPICAL ELECTRICAL CHARACTERISTICS

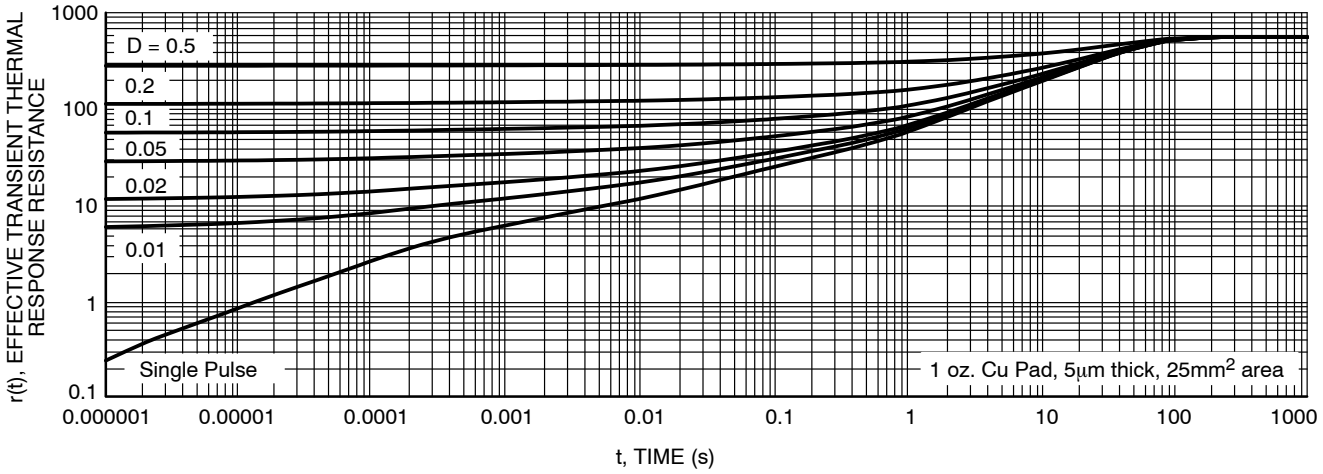
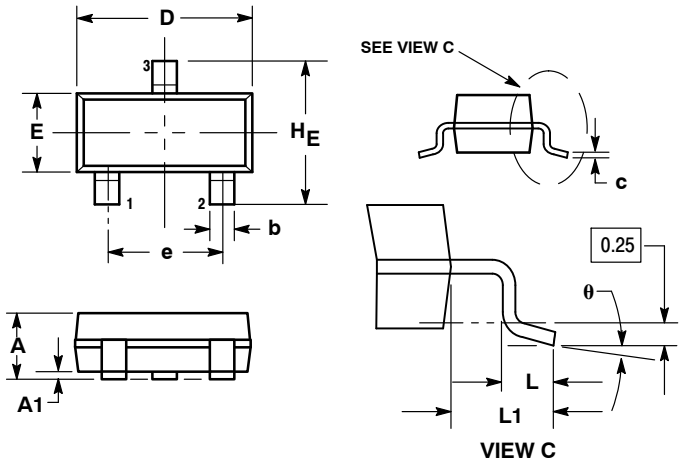


Figure 6. Thermal Response

PACKAGE DIMENSIONS

SOT−23 (TO−236)
CASE 318−08
ISSUE AP

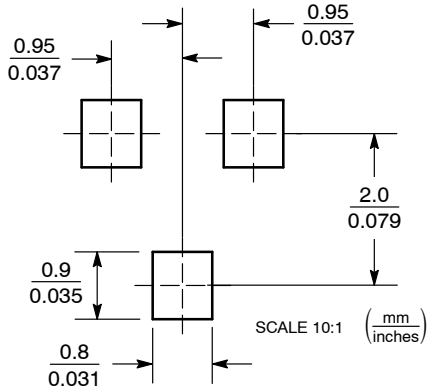


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
H_E	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°	−−−	10°	0°	−−−	10°

STYLE 21:
PIN 1. GATE
2. SOURCE
3. DRAIN

SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303−675−2175 or 800−344−3860 Toll Free USA/Canada
Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81−3−5817−1050

ON Semiconductor Website: **www.onsemi.com**

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

BSS123LT1/D

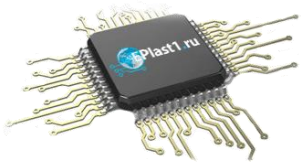
Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits,General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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